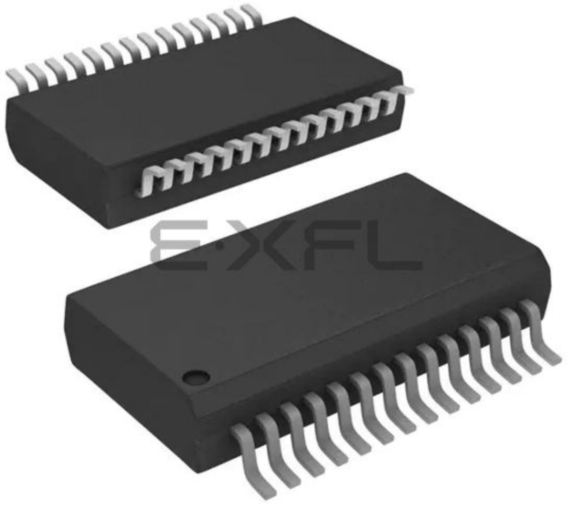
Microchip Technology - PIC32MX270F256BT-V/SS Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	19
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx270f256bt-v-ss

TABLE 7: PIN NAMES FOR 36-PIN GENERAL PURPOSE DEVICES

36-PIN VTLA (TOP VIEW)(1,2,3,5)

PIC32MX110F016C
PIC32MX120F032C
PIC32MX130F064C
PIC32MX150F128C

36

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2	19	TDO/RPB9/SDA1/CTED4/PMD3/RB9
2	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/RB3	20	RPC9/CTED7/RC9
3	PGED4(4)/AN6/RPC0/RC0	21	VSS
4	PGEC4(4)/AN7/RPC1/RC1	22	VCAP
5	VDD	23	VDD
6	VSS	24	PGED2/RPB10/CTED11/PMD2/RB10
7	OSC1/CLKI/RPA2/RA2	25	PGEC2/TMS/RPB11/PMD1/RB11
8	OSC2/CLKO/RPA3/PMA0/RA3	26	AN12/PMD0/RB12
9	SOSCI/RPB4/RB4	27	AN11/RPB13/CTPLS/PMRD/RB13
10	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	28	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/PMWR/RB14
11	RPC3/RC3	29	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
12	VSS	30	AVSS
13	VDD	31	AVDD
14	VDD	32	$\overline{\text{MCLR}}$
15	PGED3/RPB5/PMD7/RB5	33	VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/RA0
16	PGEC3/RPB6/PMD6/RB6	34	VREF-/CVREF-/AN1/RPA1/CTED2/RA1
17	TDI/RPB7/CTED3/PMD5/INT0/RB7	35	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/RB0
18	TCK/RPB8/SCL1/CTED10/PMD4/RB8	36	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/RB1

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: This pin function is not available on PIC32MX110F016C and PIC32MX120F032C devices.

5: Shaded pins are 5V tolerant.

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Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site:

- *"Using MPLAB® ICD 3"* (poster) (DS50001765)
- *"MPLAB® ICD 3 Design Advisory"* (DS50001764)
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide" (*DS50001616)
- *"Using MPLAB® REAL ICE™ Emulator"* (poster) (DS50001749)

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

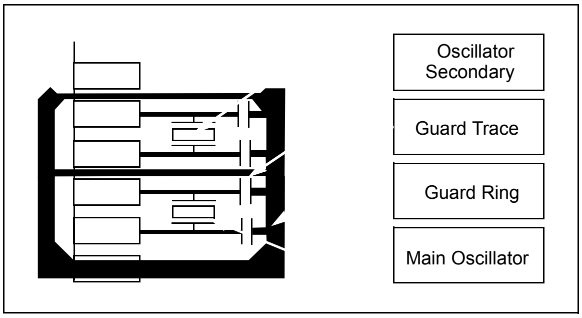
Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

2.7 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT



2.8 Unused I/Os

Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternatively, inputs can be reserved by connecting the pin to V_{SS} through a 1k to 10k resistor and configuring the pin as an input.

2.9 Typical Application Connection Examples

Examples of typical application connections are shown in Figure 2-5 and Figure 2-6.

FIGURE 2-5: CAPACITIVE TOUCH SENSING WITH GRAPHICS APPLICATION

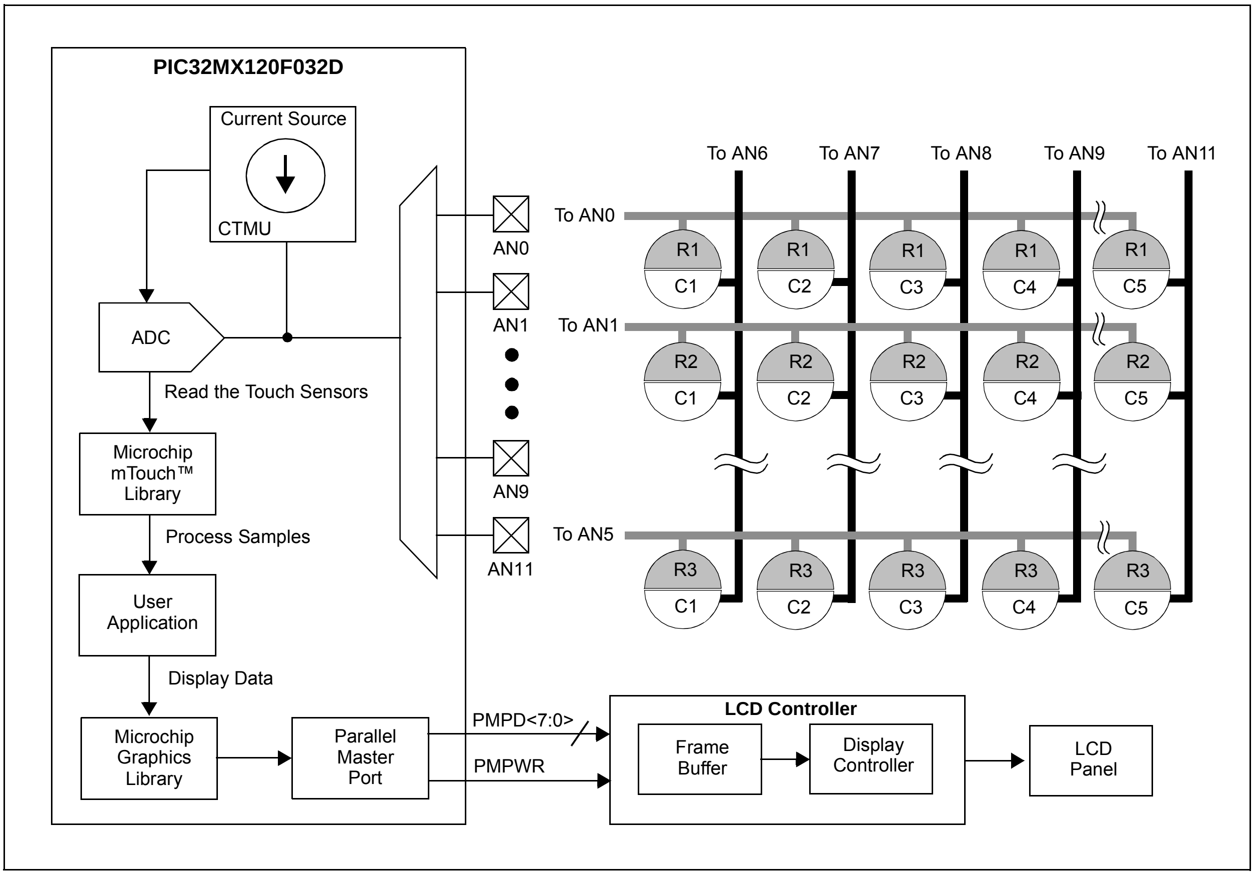
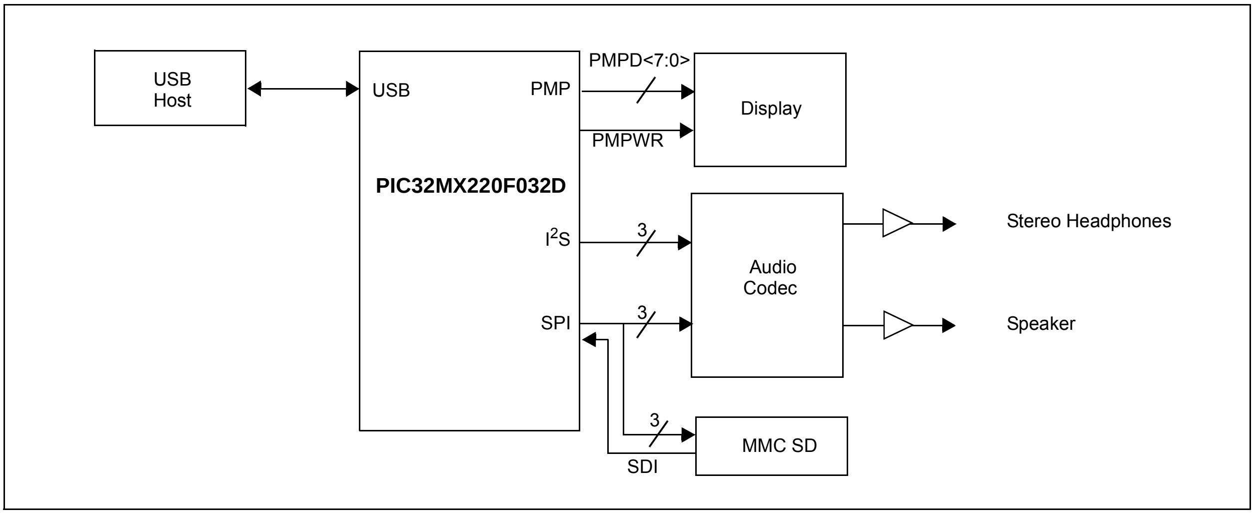


FIGURE 2-6: AUDIO PLAYBACK APPLICATION



REGISTER 7-1: INTCON: INTERRUPT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
	—	—	—	MVEC	—	TPC<2:0>		
7:0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP

Legend:
R = Readable bit　W = Writable bit　U = Unimplemented bit, read as ‘0’
-n = Value at POR　‘1’ = Bit is set　‘0’ = Bit is cleared　x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-13 **Unimplemented:** Read as ‘`0`’

bit 12 **MVEC:** Multi Vector Configuration bit
`1` = Interrupt controller configured for Multi-vectored mode
`0` = Interrupt controller configured for Single-vectored mode

bit 11 **Unimplemented:** Read as ‘`0`’

bit 10-8 **TPC<2:0>:** Interrupt Proximity Timer Control bits
`111` = Interrupts of group priority 7 or lower start the Interrupt Proximity timer
`110` = Interrupts of group priority 6 or lower start the Interrupt Proximity timer
`101` = Interrupts of group priority 5 or lower start the Interrupt Proximity timer
`100` = Interrupts of group priority 4 or lower start the Interrupt Proximity timer
`011` = Interrupts of group priority 3 or lower start the Interrupt Proximity timer
`010` = Interrupts of group priority 2 or lower start the Interrupt Proximity timer
`001` = Interrupts of group priority 1 start the Interrupt Proximity timer
`000` = Disables Interrupt Proximity timer

bit 7-5 **Unimplemented:** Read as ‘`0`’

bit 4 **INT4EP:** External Interrupt 4 Edge Polarity Control bit
`1` = Rising edge
`0` = Falling edge

bit 3 **INT3EP:** External Interrupt 3 Edge Polarity Control bit
`1` = Rising edge
`0` = Falling edge

bit 2 **INT2EP:** External Interrupt 2 Edge Polarity Control bit
`1` = Rising edge
`0` = Falling edge

bit 1 **INT1EP:** External Interrupt 1 Edge Polarity Control bit
`1` = Rising edge
`0` = Falling edge

bit 0 **INT0EP:** External Interrupt 0 Edge Polarity Control bit
`1` = Rising edge
`0` = Falling edge

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER

bit 18-16 **PLLMULT<2:0>:** Phase-Locked Loop (PLL) Multiplier bits

`111` = Clock is multiplied by 24
`110` = Clock is multiplied by 21
`101` = Clock is multiplied by 20
`100` = Clock is multiplied by 19
`011` = Clock is multiplied by 18
`010` = Clock is multiplied by 17
`001` = Clock is multiplied by 16
`000` = Clock is multiplied by 15

bit 15 **Unimplemented:** Read as ‘`0`’

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits

`111` = Internal Fast RC (FRC) Oscillator divided by FRCDIV<2:0> bits (OSCCON<26:24>)
`110` = Internal Fast RC (FRC) Oscillator divided by 16
`101` = Internal Low-Power RC (LPRC) Oscillator
`100` = Secondary Oscillator (SOSC)
`011` = Primary Oscillator (POSC) with PLL module (XTPLL, HSPLL or ECPLL)
`010` = Primary Oscillator (POSC) (XT, HS or EC)
`001` = Internal Fast RC Oscillator with PLL module via Postscaler (FRCPLL)
`000` = Internal Fast RC (FRC) Oscillator

bit 11 **Unimplemented:** Read as ‘`0`’

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits

`111` = Internal Fast RC Oscillator (FRC) divided by OSCCON<FRCDIV> bits
`110` = Internal Fast RC Oscillator (FRC) divided by 16
`101` = Internal Low-Power RC (LPRC) Oscillator
`100` = Secondary Oscillator (SOSC)
`011` = Primary Oscillator with PLL module (XTPLL, HSPLL or ECPLL)
`010` = Primary Oscillator (XT, HS or EC)
`001` = Internal Fast Internal RC Oscillator with PLL module via Postscaler (FRCPLL)
`000` = Internal Fast Internal RC Oscillator (FRC)

On Reset, these bits are set to the value of the FNOSC Configuration bits (DEVCFG1<2:0>).

bit 7 **CLKLOCK:** Clock Selection Lock Enable bit

If clock switching and monitoring is disabled (FCKSM<1:0> = `1x`):
`1` = Clock and PLL selections are locked
`0` = Clock and PLL selections are not locked and may be modified

If clock switching and monitoring is enabled (FCKSM<1:0> = `0x`):
Clock and PLL selections are never locked and may be modified.

bit 6 **ULOCK:** USB PLL Lock Status bit(1)

`1` = The USB PLL module is in lock or USB PLL module start-up timer is satisfied
`0` = The USB PLL module is out of lock or USB PLL module start-up timer is in progress or the USB PLL is disabled

bit 5 **SLOCK:** PLL Lock Status bit

`1` = The PLL module is in lock or PLL module start-up timer is satisfied
`0` = The PLL module is out of lock, the PLL start-up timer is running, or the PLL is disabled

bit 4 **SLPEN:** Sleep Mode Enable bit

`1` = The device will enter Sleep mode when a `WAIT` instruction is executed
`0` = The device will enter Idle mode when a `WAIT` instruction is executed

Note 1: This bit is only available on PIC32MX2XX devices.

> **Note:** Writes to this register require an unlock sequence. Refer to **Section 6. “Oscillator”** (DS60001112) in the *“PIC32 Family Reference Manual”* for details.

10.1 USB Control Registers

TABLE 10-1: USB REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5040	U1OTGIR(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	IDIF	T1MSECIF	LSTATEIF	ACTVIF	SESVDIF	SESENDIF	—	VBUSVDIF	0000
5050	U1OTGIE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	IDIE	T1MSECIE	LSTATEIE	ACTVIE	SESVDIE	SESENDIE	—	VBUSVDIE	0000
5060	U1OTGSTAT(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	ID	—	LSTATE	—	SESVD	SESEND	—	VBUSVD	0000
5070	U1OTGCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	DPPULUP	DMPULUP	DPPULDWN	DMPULDWN	VBUSON	OTGEN	VBUSCHG	VBUSDIS	0000
5080	U1PWRC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	UACTPND(4)	—	—	USLPGRD	USBBUSY	—	USUSPEND	USBPWR	0000
5200	U1IR(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	STALLIF	ATTACHIF	RESUMEIF	IDLEIF	TRNIF	SOFIF	UERRIF	URSTIF DETACHIF	0000 0000
5210	U1IE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	STALLIE	ATTACHIE	RESUMEIE	IDLEIE	TRNIE	SOFIE	UERRIE	URSTIE DETACHIE	0000 0000
5220	U1EIR(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BTSEF	BMXEF	DMAEF	BTOEF	DFN8EF	CRC16EF	CRC5EF EOFEF	PIDEF	0000 0000
5230	U1EIE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BTSEE	BMXEE	DMAEE	BTOEE	DFN8EE	CRC16EE	CRC5EE EOFEE	PIDEE	0000 0000
5240	U1STAT(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	ENDPT<3:0>				DIR	PPBI	—	—	0000
5250	U1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	JSTATE	SE0	PKTDIS TOKBUSY	USBRST	HOSTEN	RESUME	PPBRST	USBEN SOFEN	0000 0000
5260	U1ADDR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	LSPDEN	DEVADDR<6:0>							0000
5270	U1BDTP1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BDTPTRL<15:9>							—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: With the exception of those noted, all registers in this table (except as noted) have corresponding CLR, SET and INV registers at their virtual address, plus an offset of 0x4, 0x8, and 0xC respectively. See **Section 11.2 “CLR, SET and INV Registers”** for more information.

2: This register does not have associated SET and INV registers.

3: This register does not have associated CLR, SET and INV registers.

4: Reset value for this bit is undefined.

REGISTER 10-11: U1CON: USB CONTROL REGISTER (CONTINUED)

bit 1 **PPBRST:** Ping-Pong Buffers Reset bit

`1` = Reset all Even/Odd buffer pointers to the EVEN Buffer Descriptor banks
`0` = Even/Odd buffer pointers are not Reset

bit 0 **USBEN:** USB Module Enable bit(4)

`1` = USB module and supporting circuitry is enabled
`0` = USB module and supporting circuitry is disabled

SOFEN: SOF Enable bit(5)

`1` = SOF token is sent every 1 ms
`0` = SOF token is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 10-15).

2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

5: Host mode.

REGISTER 11-1: [*pin name*]R: PERIPHERAL PIN SELECT INPUT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	[*pin name*]R<3:0>			

Legend:

R = Readable bit　W = Writable bit　U = Unimplemented bit, read as ‘0’

-n = Value at POR　‘1’ = Bit is set　‘0’ = Bit is cleared　x = Bit is unknown

bit 31-4 **Unimplemented:** Read as ‘`0`’

bit 3-0 **[*pin name*]R<3:0>:** Peripheral Pin Select Input bits

Where [*pin name*] refers to the pins that are used to configure peripheral input mapping. See Table 11-1 for input pin selection values.

Note: Register values can only be changed if the Configuration bit, IOLOCK (CFGCON<13>), = `0`.

REGISTER 11-2: RPnR: PERIPHERAL PIN SELECT OUTPUT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	RPnR<3:0>			

Legend:

R = Readable bit　W = Writable bit　U = Unimplemented bit, read as ‘0’

-n = Value at POR　‘1’ = Bit is set　‘0’ = Bit is cleared　x = Bit is unknown

bit 31-4 **Unimplemented:** Read as ‘`0`’

bit 3-0 **RPnR<3:0>:** Peripheral Pin Select Output bits

See Table 11-2 for output pin selection values.

Note: Register values can only be changed if the Configuration bit, IOLOCK (CFGCON<13>), = `0`.

14.1 Watchdog Timer Control Registers

TABLE 14-1: WATCHDOG TIMER CONTROL REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0000	WDTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	—	—	—	—	—	—	SWDTPS<4:0>					WDTWINEN	WDTCLR	0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET and INV Registers”** for more information.

18.1 I2C Control Registers

TABLE 18-1: I2C1 AND I2C2 REGISTER MAP

Virtual Address (BF80_#)	Register Name[1]	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5000	I2C1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5010	I2C1STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
5020	I2C1ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Register										0000
5030	I2C1MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Mask Register										0000
5040	I2C1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	Baud Rate Generator Register												0000
5050	I2C1TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Transmit Register								0000
5060	I2C1RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Receive Register								0000
5100	I2C2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5110	I2C2STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
5120	I2C2ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Register										0000
5130	I2C2MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Mask Register										0000
5140	I2C2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	Baud Rate Generator Register												0000
5150	I2C2TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Transmit Register								0000
5160	I2C2RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Receive Register								0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table except I2CxRCV have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET and INV Registers”** for more information.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
	EDG2MOD	EDG2POL	EDG2SEL<3:0>				—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ON	—	CTMUSIDL	TGEN(1)	EDGEN	EDGSEQEN	IDISSEN(2)	CTTRIG
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ITRIM<5:0>						IRNG<1:0>	

Legend:
R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR
‘1’ = Bit is set
‘0’ = Bit is cleared
x = Bit is unknown

bit 31 **EDG1MOD:** Edge1 Edge Sampling Select bit
`1` = Input is edge-sensitive
`0` = Input is level-sensitive

bit 30 **EDG1POL:** Edge 1 Polarity Select bit
`1` = Edge1 programmed for a positive edge response
`0` = Edge1 programmed for a negative edge response

bit 29-26 **EDG1SEL<3:0>:** Edge 1 Source Select bits
`1111` = C3OUT pin is selected
`1110` = C2OUT pin is selected
`1101` = C1OUT pin is selected
`1100` = IC3 Capture Event is selected
`1011` = IC2 Capture Event is selected
`1010` = IC1 Capture Event is selected
`1001` = CTED8 pin is selected
`1000` = CTED7 pin is selected
`0111` = CTED6 pin is selected
`0110` = CTED5 pin is selected
`0101` = CTED4 pin is selected
`0100` = CTED3 pin is selected
`0011` = CTED1 pin is selected
`0010` = CTED2 pin is selected
`0001` = OC1 Compare Event is selected
`0000` = Timer1 Event is selected

bit 25 **EDG2STAT:** Edge2 Status bit
Indicates the status of Edge2 and can be written to control edge source
`1` = Edge2 has occurred
`0` = Edge2 has not occurred

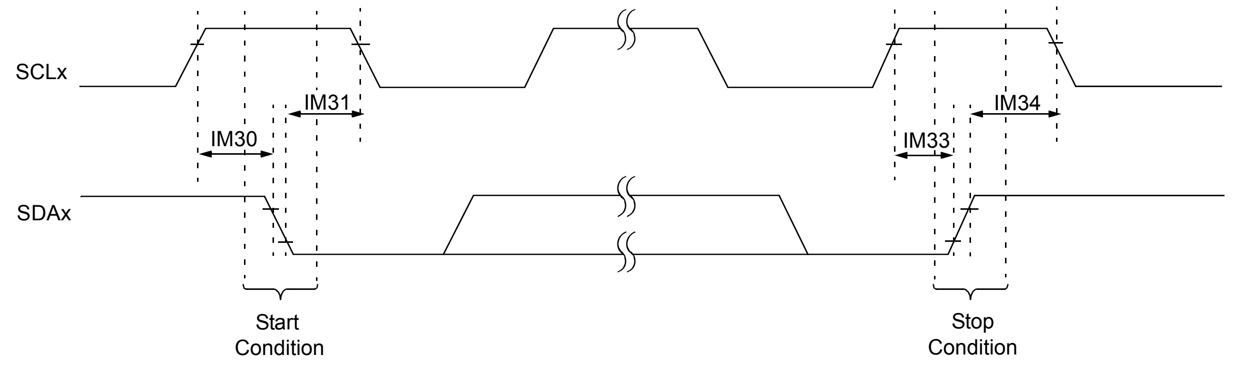
Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to ‘`1110`’ to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘`1`’, performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 “Electrical Characteristics”** for current values.

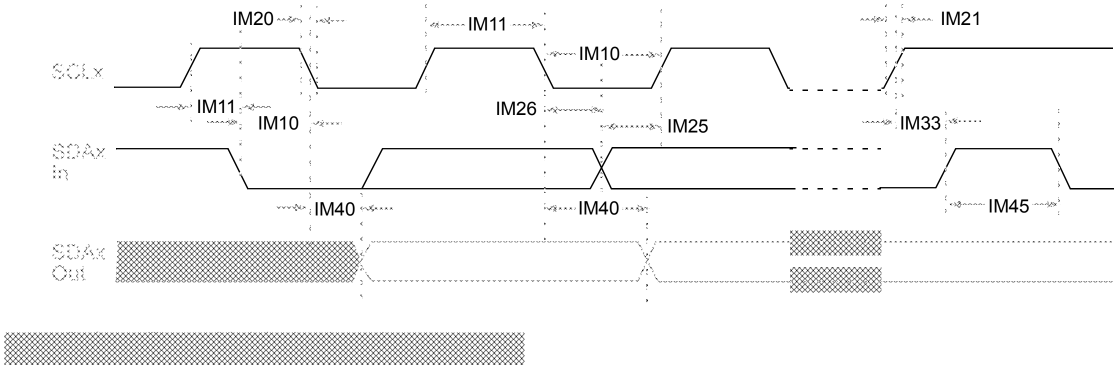
4: This bit setting is not available for the CTMU temperature diode.

FIGURE 30-14: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 30-1 for load conditions.

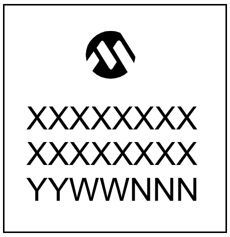
FIGURE 30-15: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



NOTES:

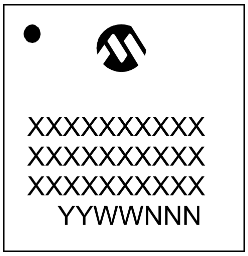
33.1 Package Marking Information (Continued)

36-Lead VTLA

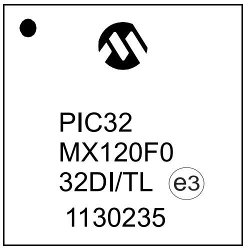


Example

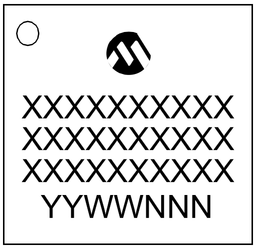
44-Lead VTLA



Example

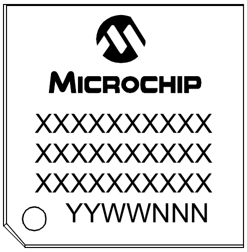


44-Lead QFN

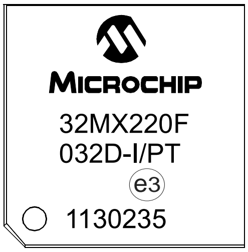


Example

44-Lead TQFP



Example

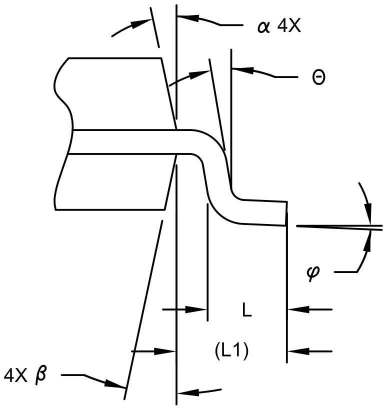


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

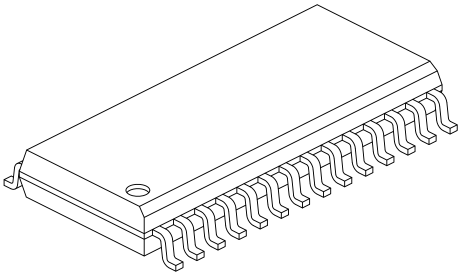
Note: If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

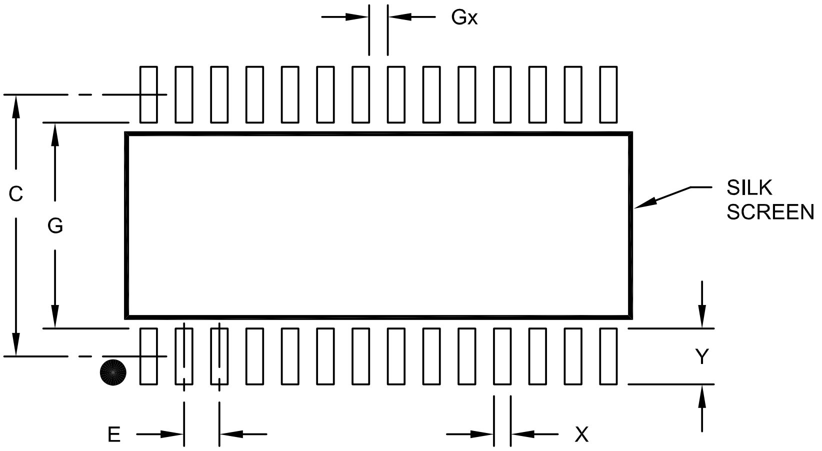
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

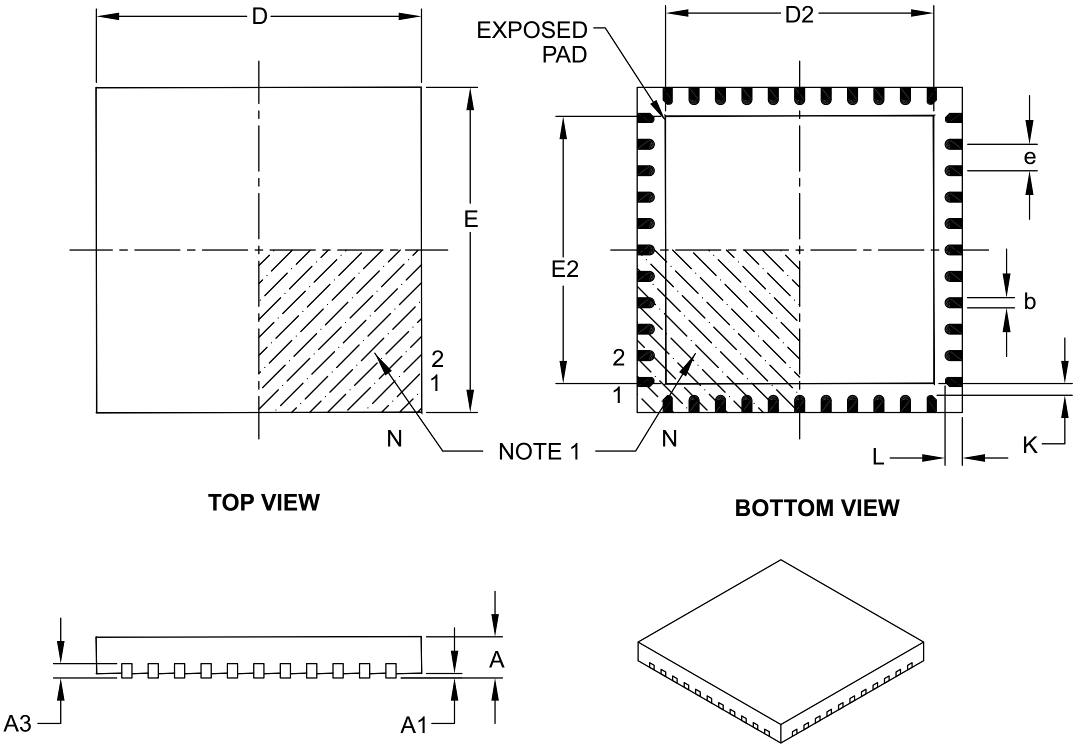
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

Revision G (April 2015)

This revision includes the addition of the following devices:

- PIC32MX130F256B
- PIC32MX130F256D
- PIC32MX230F256B
- PIC32MX230F256D

The title of the document was updated to avoid confusion with the PIC32MX1XX/2XX/5XX 64/100-pin Family data sheet.

All peripheral SFR maps have been relocated from the Memory chapter to their respective peripheral chapters.

In addition, this revision includes the following major changes as described in Table A-6, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-6: MAJOR SECTION UPDATES

Section	Update Description
32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog	Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see Pin Diagrams).
2.0 “Guidelines for Getting Started with 32-bit MCUs”	Updated these sections: **2.2 “Decoupling Capacitors”**, **2.3 “Capacitor on Internal Voltage Regulator (VCAP)”**, **2.4 “Master Clear (MCLR) Pin”**, **2.8.1 “Crystal Oscillator Design Consideration”**
4.0 “Memory Organization”	Added Memory Map for new devices (see Figure 4-6).
14.0 “Watchdog Timer (WDT)”	New chapter created from content previously located in the Special Features chapter.
30.0 “Electrical Characteristics”	Removed parameter D312 (TSET) from the Comparator Specifications (see Table 30-12). Added the Comparator Voltage Reference Specifications (see Table 30-13). Updated Table 30-12.

Revision H (July 2015)

This revision includes the following major changes as described in Table A-7, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-7: MAJOR SECTION UPDATES

Section	Update Description
2.0 “Guidelines for Getting Started with 32-bit MCUs”	**Section 2.9 “Sosc Design Recommendation”** was removed.
8.0 “Oscillator Configuration”	The Primary Oscillator (POSC) logic in the Oscillator diagram was updated (see Figure 8-1).
30.0 “Electrical Characteristics”	The Power-Down Current (IPD) DC Characteristics parameter DC40k was updated (see Table 30-7). **Table 30-9: “DC Characteristics: I/O Pin Input Injection current Specifications”** was added.

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